

(2)

N-Ch MOSFET

General Description

The WSR20N20 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSR20N20 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

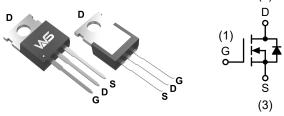
Product Summery

BV _{DSS}	R _{DSON}	I _D
200V	120mΩ	20A

Applications

- High Frequency Point-of-Load Synchronous
 Buck Converter
- Networking DC-DC Power System
- Load Switch





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	200	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	20	А
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	11	А
I _{DM}	Pulsed Drain Current ²	72	А
EAS	Single Pulse Avalanche Energy ³	340	mJ
PD	Total Power Dissipation ³	104	W
T _{STG}	Storage Temperature Range	-55 to 175	°C
TJ	Operating Junction Temperature Range -55 to 175		°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{0JA}	Thermal Resistance Junction-ambient ¹		62.5	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹		1.2	°C/W



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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	200			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=1mA		0.098		V/℃
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V_{GS} =10V , I_{D} =9A		120	150	mΩ
V _{GS(th)}	Gate Threshold Voltage		2.0	3.0	4.0	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS, ID -2500A		-4.57		mV/℃
	Drain Source Lookage Current	V_{DS} =160V , V_{GS} =0V , TJ=25 $^\circ\!\mathrm{C}$	1		1	
I _{DSS}	Drain-Source Leakage Current	V_{DS} =160V , V_{GS} =0V , TJ=55 $^\circ\!\mathrm{C}$			5	uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm25V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =9A		32		S
Qg	Total Gate Charge (10V)			41		
Q _{gs}	Gate-Source Charge V_{DS} =100V , V_{GS} =10V , I_{D} =18A			5.5		nC
Q _{gd}	Gate-Drain Charge			75		
T _{d(on)}	Turn-On Delay Time			24		
Tr	Rise Time V _{DD} =30V , V _{GS} =10V ,			45		
T _{d(off)}	Turn-Off Delay Time	R _G =6Ω, I _D =18A, R∟=30Ω		95		ns
T _f	Fall Time			101		
C _{iss}	Input Capacitance			1318		
Coss	Output Capacitance	V _{DS} =30V , V _{GS} =0V , f=1MHz		180		рF
C _{rss}	Reverse Transfer Capacitance			75		

Diode Characteristics

Symbol	Parameter Conditions		Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}				18	А
I _{SM}	Pulsed Source Current ^{2,6}	$V_G = V_D = 0V$, Force Current			72	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =18A , Tյ=25℃			1.2	V
t _{rr}	Reverse Recovery Time			230		nS
Qrr	Reverse Recovery Charge	IF=18A , dI/dt=100A/µs , Tյ=25℃		1800		nC

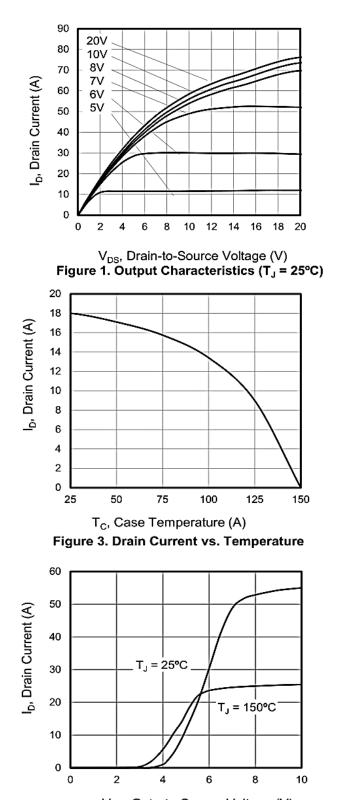
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition: Tj=25 $^\circ\!\mathrm{C}$,V_DD=50V,V_G=10V,L=0.5mH,Rg=25 Ω

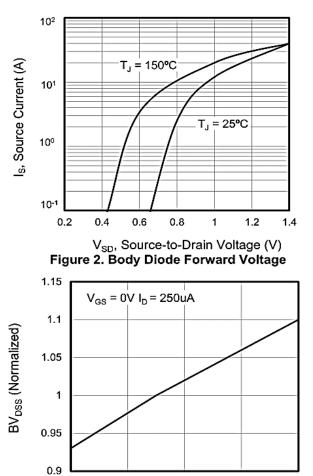


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Typical Characteristics







T_J, Junction Temperature (°C) Figure 4. BV_{DSS} Variation vs. Temperature

50

100

150

-50

0

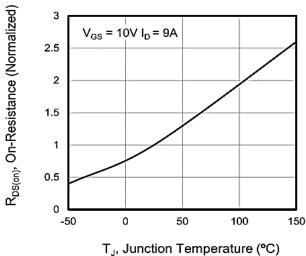
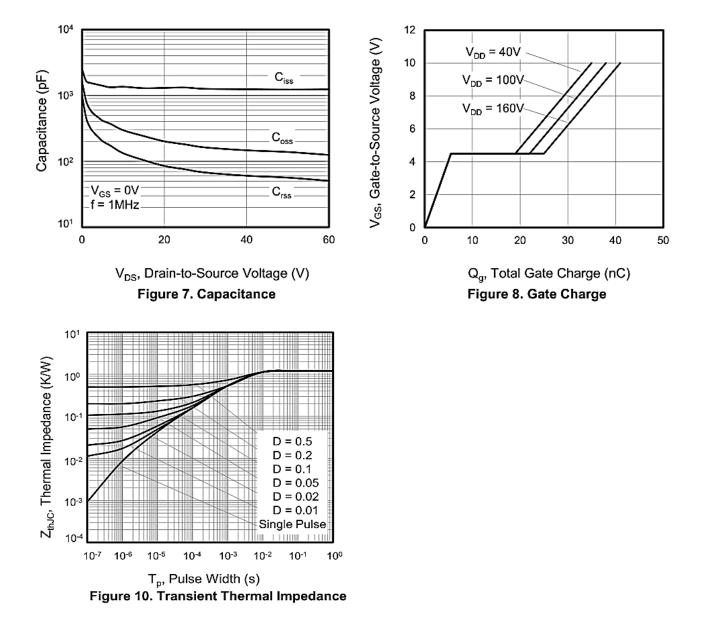


Figure 6. On-Resistance vs. Temperature



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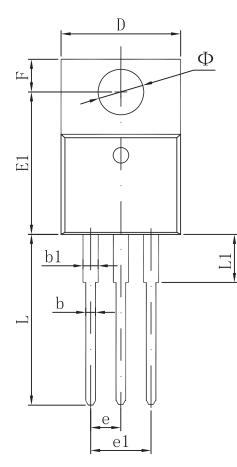
Typical Characteristics

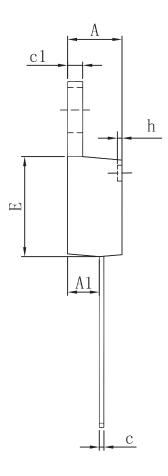




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Packaging information





Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Мах	Min	Max	
А	4.470	4.670	0.176	0.184	
A1	2.520	2.820	0.099	0.111	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
Е	8.500	8.900	0.335	0.350	
E1	12.060	12.460	0.475	0.491	
е	2.540	2.540 TYP) TYP	
e1	4.980	5.180	0.196	0.204	
F	2.590	2.890	0.102	0.114	
h	0.000	0.300	0.000	0.012	
L	13.400	13.800	0.528	0.543	
L1	3.560	3.960	0.140	0.156	
Ф	3.735	3.935	0.147	0.155	



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